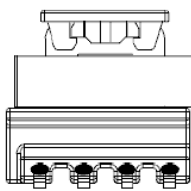
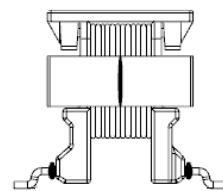


Transformer

Material Data Sheet

Product Class:	SMD E10 EM B78307AxxxxA003	 
Date	28.11.2018	
IMDS ID if available		
Version:	04	

Product Part (IMDS: semi component)	Material Class (IMDS: Material)	Material (Classification) VDA 231	Substance	TMPS** [wt%]	CAS if applicable	typical mass of material [wt-%]	Traces see 1)
Active Part	Ceramic	4B	Manganese Zinc Ferrite	100	12645-49-7	58.5	
	Heavy Metal	1C	Cu	100	7440-50-8	8.1	
	Heavy Metal	1C	Sn	100	7440-31-5	0.2	
	Thermoplastic	2A	Ethylene tetrafluoroethylene(ETFE)	100	25038-71-5	0.6	
Encapsulation and Mounting	Thermoplastic	2A	Phenolic	35-50	9003-35-4	17.6	
			Glass fiber	50-65	65997-17-3		
	Thermoplastic	2A	Liquid crystal polymer (LCP)	60	90967-43-4	4.2	
			Glass fiber	40	65997-17-3		
	Duromer	2C	Epoxy	100	25928-94-3	0.2	
	Duromer	2C	Polyimide	100	60842-76-4	6.1	
	Duromer	2C	Acrylic polymer	100	9017-68-9	0.4	
	Heavy Metal	1C	Sn	100	7440-31-5	1.2	
Termination	Heavy Metal	1C	Cu	94	7440-50-8	2.8	
		1C	Sn	6	7440-31-5		
	Heavy Metal	1C	Ni	100	7440-02-0		x
	Heavy Metal	1C	Sn	100	7440-31-5	0.1	

Sum in total: 100.0

Size W x L x H [max. in mm]	Weight [approx. in g]	Part Numbers	Size W x L x H [max. in mm]	Weight [approx. in g]	Part Numbers
11.7x9.3x11.35	2.0	B78307A2338A003;P100878	11.7x9.3x11.35	1.9	B78307A2276A003;P100403
11.7x9.3x11.35	2.0	B78307A2385A003;P300992	11.7x9.3x11.35	1.9	B78307A2277A003;P100494
11.7x9.3x11.35	1.9	B78307A9741A003;P301519			

Not part of a Product Class : ---

Contact	Dr. Johann Reindl, MAG EPQM	Important remarks: 1) The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906) Traces are product parts, substances etc. that are below a percentage of 0.1 % by weight, if not otherwise regulated 2) This Material Data Sheet contains typical values of the respective products set forth herein. We expressly point out that all values and statements contained herein are based on our best present knowledge and cannot be regarded as binding statements or binding product specifications, unless otherwise explicitly agreed in writing. TDK ELECTRONICS AG AND ITS AFFILIATES HEREBY EXPRESSLY DISCLAIM ANY REPRESENTATION OR WARRANTY, WHETHER EXPRESS, IMPLIED OR STATUTORY, WITH REGARD TO THE STATEMENTS AND VALUES CONTAINED HEREIN, INCLUDING BUT NOT LIMITED TO ANY REPRESENTATION OR WARRANTY OF MERCHANTABILITY OR SUITABILITY FOR ANY PURPOSE.
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*) others: (not declarable or prohibited substances acc. GADSL)		
**) typical mass percentage of substance		

The products set forth herein are "RoHS-compatible". RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

RoHS - Exemptions for the product class / product according to Annex III: (valid not valid)

no exemptions;

- Exemption 6 (a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight;
- Exemption 6 (b): Lead as an alloying element in aluminium containing up to 0,4 % lead by weight;
- Exemption 6 (c): Copper alloy containing up to 4 % lead by weight;
- Exemption 7 (a): Lead in high melting temperature type solder (i.e. lead-based alloys containing 85 % by weight or more lead);
- Exemption 7 (c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound;
- Exemption 7 (c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher;
- Exemption 7 (c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC;
- Exemption 15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages;
- Other Exemption than above

